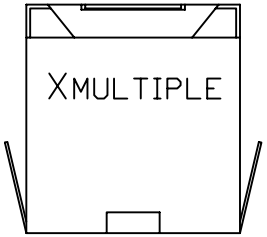
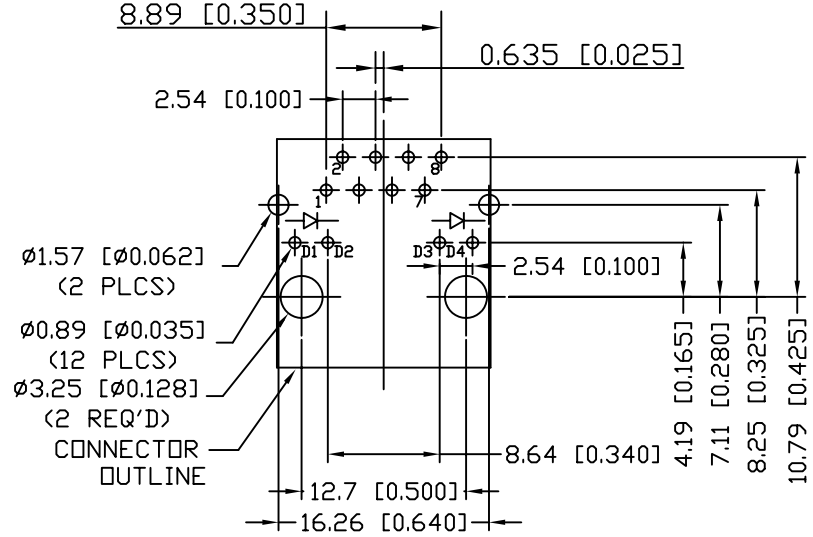
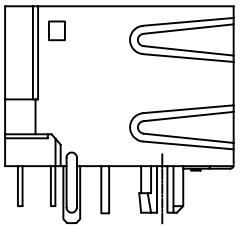
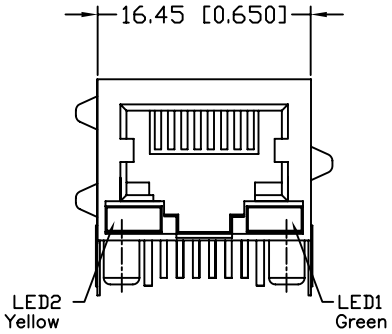
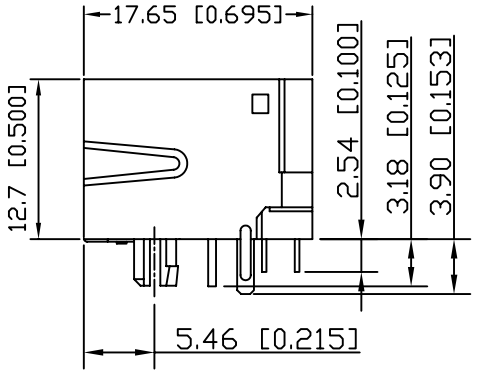




SUGGESTED PCB LAYOUT
TOP VIEW







NOTES:

1. MATERIALS:
   HOUSING: HIGH TEMP. THERMOPLASTIC, BLACK, UL 94V-0
   CONTACTS: 0.014 INCHES (0.35 MINIMETERS) THICK PHOSPHOR BRONZE PLATED WITH
   ⚠ 100 MICROINCHES(2.54 MICROMETERS) MINIMUM THICK TIN IN SOLDER AREA.
   50 MICROINCHES (1.27 MICROMETERS) MINIMUM GOLD IN LOCALIZED PLATE AREA.
   ENTIRE CONTACTS PLATED WITH 50 MICROINCHES (1.27 MICROMETERS) MINIMUM THICK NICKEL.
   SHIELDED: 0.0098 INCHES(0.25 MINIMETERS) THICK COPPER ZINC ALLOY PLATED WITH
   30 MICROINCHES (0.762 MICROMETERS) MINIMUM THICK NICKEL
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F
3. UNSPECIFIED TOLERANCE: .XX ±0.25[0.010]
   .X ±0.30[0.012]

RoHS Compliant

XMULTIPLE — CONNECTING THE INFORMATION AGE

XMULTIPLE ASIA
4F, No. 347,Yang Guang St.,
Neihu Chiu , Taipei , Taiwan 11475

XMULTIPLE USA
543 Country Club Drive #B 128
Simi Valley, CA 93065

THIS DRAWING IS A CONTROLLED DOCUMENT.

G/NO:	
DWG NO:	XRJDB-S-01-8-8-1-MT50
TITLE:	Stacked RJ45 Connectors, W/LED,8P,8C,Shielded, Thru Hole
DRAWN:	RUNES
PART NO:	XRJDB-S-01-8-8-1-MT50
CHKD:	JEFF
DATE:	Jan.26,06

UNIT	SHEET	REV
mm[inch]	1 of 1	C